

Editorial Contact:
Lori Mesecke/Christine Antles
Email: pr@pcisig.com



PCI-SIG® RELEASES PCI EXPRESS® M.2 SPECIFICATION REVISION 1.0

M.2 next-generation form factor provides scalable performance for power-constrained platforms, such as smartphones and tablets

BEAVERTON, Ore. – December 12, 2013 – [PCI-SIG®](http://www.pcisig.com), the organization responsible for the widely adopted [PCI Express®](http://www.pcisig.com) (PCIe®) industry-standard input/output (I/O) technology, today announced the release of the PCIe M.2 Specification Revision 1.0 to its members. A next-generation form factor for ultra-light and thin platforms, the latest M.2 architecture increases design flexibility to support high-end performance and enhanced data rates for power-constrained platforms. In addition, it enables the higher integration of functions onto a single form factor module solution.

As a natural progression from PCIe® Mini Card and PCIe® Half Mini Card, the smaller M.2 form factor is designed to meet future market requirements for applications in thin mobile platforms, such as tablets, portable gaming devices, smartphones and devices requiring SSDs. Its extensible design provides scalability for multiple technologies and host interfaces, including Wi-Fi®, Bluetooth®, SSD and WWAN.

“As users switch from legacy PCs to compact mobile devices, their demand for robust and power-efficient computing platforms endures,” said Al Yanes, PCI-SIG chairman and president. “The M.2 form factor offers tunable I/O technology, allowing developers to create the optimal balance of power and performance in their platform implementations.”

The new M.2 specification allows for the manufacturing of larger PCBs, maximizing the use of the card space and leaving behind a minimal footprint. The specification also helps to address the demand for mobile device I/O solutions with new specifications targeted at ultra-light and thin platforms.

Revision 1.0 M.2 connectors support both single- and double-sided module cards and are available in connectorized or soldered-down forms. The connectorized forms allow single-sided modules for low profile solutions, or dual-sided modules for increased integration within the platform. All soldered-down module cards are single-sided and are intended for use in low profile applications.

Members can download the PCIe M.2 specification at www.pcisig.com.

Join PCI-SIG

PCI-SIG members can participate in the review of all PCI specifications before they are released to the industry. PCI-SIG members develop and maintain PCIe specifications, including the PCIe 4.0 specification, and are actively involved in defining compliance criteria and other technical enabling collateral.

As an additional and extremely valuable benefit of PCI-SIG membership, members are given the right to receive patent licenses from any other member of the organization with necessary claims of patent embodied within the specifications. These licenses may be limited in scope to an implementation of a particular specification, but must be granted to all members on reasonable and non-discriminatory terms. To join the PCI-SIG, visit

www.pcisig.com/membership.

About PCI-SIG

PCI-SIG is the consortium that owns and manages PCI specifications as open industry standards. The organization defines industry standard I/O (input/output) specifications consistent with the needs of its members. Currently, PCI-SIG is comprised of nearly 800 industry-leading member companies. To join PCI-SIG, and for a list of the Board of Directors, visit www.pcisig.com.

PCI-SIG, PCI Express, PCIe and M-PCIe are trademarks or registered trademarks of PCI-SIG. All other trademarks are the property of their respective owners.

###